١.		Search	rch Text	DBs	Time Stamp	Comments	FILOT DOLLAR	S H	
	H158	257/782.ccls. Of	257/783.ccls.	T; GPU PO; IENT	2001/09/19 12:09			0	
	134	Ll and( die an adhesive)	and substrate and	T; GPU PO; ENT	2001/09/19 12:11			o	3
:	134	L1 and (die a' adhesive)	and (die and substrate and sesive)	USPAT: US-PGPU US-PGPU B; EPO; 2 UPO; UDERWENT ; IBM	2001/09/19			0	
	1	L3 and (bisme adhesive)	(bismaleimide near	AT; PGPU EPO; ; WENT BM	2001/09/19 12:15	-		0	<i>\$</i>
		substrate and die (bismaleimide wit (solder adj mask)	d die and le with adhesive) and mask)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM	2001/09/19 12:19			0	
1.6	129	substrate and (bismaleimide	nd die and de same adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM	2001/09/19			0	•
17	46	substrate and die	nd die and .de with adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM	2001/09/19 12:25			0	
1 75	L8 2	L7 and ((pu	((prevent or enhance or or or benefit) with adhesive)		U 2001/09/19 12:28			0	

Type	#	Hits	Search Text	DBs	Time Stamp (	Comments	Error Definition	rs
BRS	1.9	0	L7 and ((prevent or enhance or impove or benefit) with (bmi or bismeleimide))	D . L	2001/09/19 12:29			0
BRS	L10	0	L7 and ((prevent or enhance or impove or benefit) same (bmi or bismeleimide))	D * H	2001/09/19 12:29			0
BRS	L11	16	USE adhesive and ((prevent or enhance B; or improve or benefit) same (bmi JPC or bismeleimide))	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM	2001/09/19 12:51			0
BRS	L12	œ	L11 and (die or chip or semiconductor)	USPAT; US-PGPU B; EPO; JPO; DENWENT ; IBM	2001/09/19 12:50			0
BRS	113	16	adhesive and ((prevent or enhance or improve or benefit) same (bmi or bismalamide))		2001/09/19 12:50			0
BRS	L14	8	L13 and (die or chip or semiconductor)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:53			0
BRS	L15	247	(adhesive with (bmi or bism\$)) and (prevent or impove or increase or advantage or benefit)		2001/09/19 13:39		Truncation Overflow Return string from Server is: 5`660354`	П
BRS	1.16	8.7	L15 and (die or chip or semiconductor)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM	2001/09/19 12:55			0

Type	н	#	Hits	Search Text	DBs	Time Stamp C	Comments	Error Definition	rs
	17		788	257/782.ccls. or 257/783.ccls.	D's E	2001/09/19 12:09			0
	1.2		134	L1 and( die and substrate and adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM	2001/09/19 12:11			0
			134	L1 and (die and substrate and adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM	2001/09/19 12:11			0
	L 4		1	L3 and (bismaleimide near adhesive)	D . F	2001/09/19 12:15			0
	L5		П	substrate and die and (bismaleimide with adhesive) and (solder adj mask)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM	2001/09/19 12:19			0
	16		129	substrate and die and (bismaleimide same adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM	2001/09/19 12:19			0
	L7		46	substrate and die and (bismaleimide with adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM	2001/09/19 12:25			0
	F.8		2	L7 and ((prevent or enhance or impove or benefit) with adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT; IBM	2001/09/19 12:28			0

		4 + -7	Search Text	DBs	Time Stamp Cor	Comments	Error Delinition	N H
<b>러</b>			or enhance or uith (bmi or	AT; PGPU EPO; D; WENT	2001/09/19 12:29			0
110	0	0	U U U U U U U U U U U U U U U U U U U	AT; PGPU EPO; MENT MENT BM	2001/09/19 12:29			0
Н	L11	16	uSPAT; uSPAT; uSPECT (SPECT OF ENDANCE B: BFO; or improve or benefit) same (bmi JPO; or bismeleimide)); IBM		2001/09/19 12:51			0
	L12	8	L11 and (die or chip or semiconductor)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM	2001/09/19 12:50			0
	L13	16	adhesive and ((prevent or enhance B; EPO; or improve or benefit) same (bmi JPO; or bismalamide)); IBM	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:50			0
	L14	80	L13 and (die or chip or semiconductor)	USPAT; US-PGPU B; EPO; JPO; DERWENT; IBM	2001/09/19			0
1	L15	247	(adhesive with (bmi or bism\$)) and (prevent or impove or increase or advantage or benefit)		, 2001/09/19 1 13:39		Truncation Overflow. Return string from Server is: 5.660354`	
1	L16	87	L15 and (die or chip or semiconductor)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM	U 7 2001/09/19 T 12:55			0

	Type	# 1	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Erro
17	BRS	L17	e .	(adhesive with (bmi or bism\$)) with (moisture or break\$)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM	2001/09/19 13:42		Truncation Overflow. Return string from Server is: 5`660354`	H
18	BRS	L18	25	257/783.ccls. and (bmi or bism\$) USPAT		2001/09/19 14:35			0
19	BRS	L19	228	(adesion or adhesive) with (bmi or USPAT bism\$)		2001/09/19 14:07			0
20	BRS	L20	372	(adhesion or adhesive) with (bmi or bism\$)	USPAT	2001/09/19 14:13			0
21	BRS	L21	88	L20 and semiconductor	USPAT	2001/09/19 14:08			0
22	BRS	L22	44		USPAT	2001/09/19 14:08			0
23	BRS	1.23	273	_	USPAT	2001/09/19 14:33			0
24	BRS	L24	410	(chip or die) and (solder adj mask) and adhesive	USPAT	2001/09/19 14:34			0
25	BRS	L25	61	124 and (bmi or bism\$)	USPAT	2001/09/19 14:35			0